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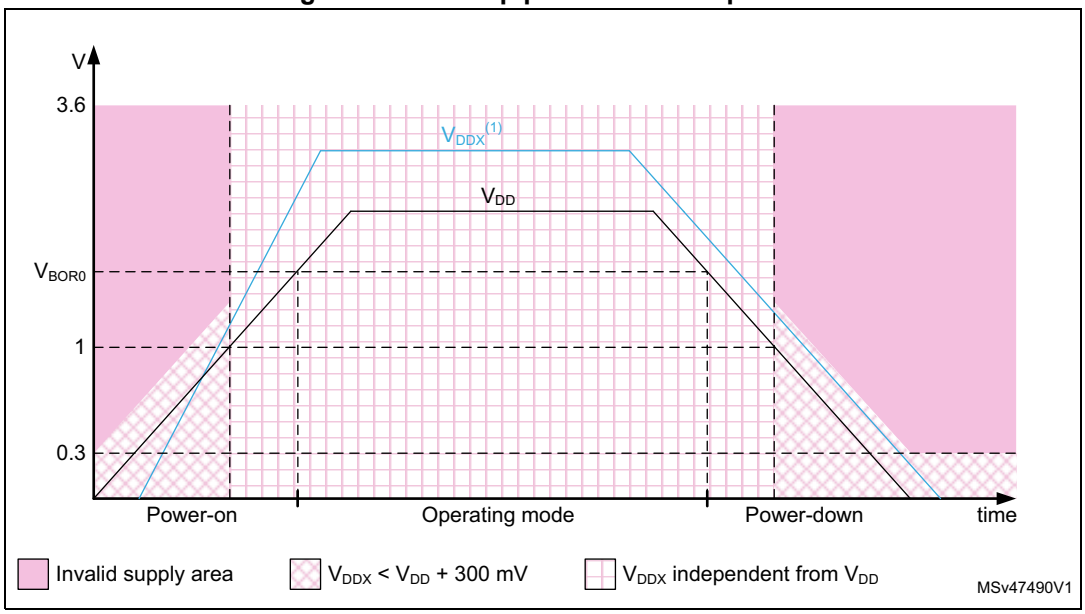
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M7
Core Size	32-Bit Single-Core
Speed	480MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, LINbus, MDIO, MMC/SD/SDIO, QSPI, SAI, SPDIF, SPI, SWPMI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, LCD, POR, PWM, WDT
Number of I/O	168
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1M x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 36x16b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	265-TFBGA
Supplier Device Package	240+25-TFBGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32h750xbh6

Figure 2. Power-up/power-down sequence



1. V_{DDx} refers to any power supply among V_{DDA}, $V_{DD33USB}$, $V_{DD50USB}$.

3.5.2 Power supply supervisor

The devices have an integrated power-on reset (POR)/ power-down reset (PDR) circuitry coupled with a Brownout reset (BOR) circuitry:

- Power-on reset (POR)

  The POR supervisor monitors V_{DD} power supply and compares it to a fixed threshold. The devices remain in Reset mode when V_{DD} is below this threshold,

- Power-down reset (PDR)

  The PDR supervisor monitors V_{DD} power supply. A reset is generated when V_{DD} drops below a fixed threshold.

  The PDR supervisor can be enabled/disabled through PDR_ON pin.

- Brownout reset (BOR)

  The BOR supervisor monitors V_{DD} power supply. Three BOR thresholds (from 2.1 to 2.7 V) can be configured through option bytes. A reset is generated when V_{DD} drops below this threshold.

3.7.2 System reset sources

Power-on reset initializes all registers while system reset reinitializes the system except for the debug, part of the RCC and power controller status registers, as well as the backup power domain.

A system reset is generated in the following cases:

- Power-on reset (pwr_por_rst)
- Brownout reset
- Low level on NRST pin (external reset)
- Window watchdog
- Independent watchdog
- Software reset
- Low-power mode security reset
- Exit from Standby

3.8 General-purpose input/outputs (GPIOs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain, with or without pull-up or pull-down), as input (floating, with or without pull-up or pull-down) or as peripheral alternate function. Most of the GPIO pins are shared with digital or analog alternate functions. All GPIOs are high-current-capable and have speed selection to better manage internal noise, power consumption and electromagnetic emission.

After reset, all GPIOs (except debug pins) are in Analog mode to reduce power consumption (refer to GPIOs register reset values in the device reference manual).

The I/O configuration can be locked if needed by following a specific sequence in order to avoid spurious writing to the I/Os registers.

3.9 Bus-interconnect matrix

The devices feature an AXI bus matrix, two AHB bus matrices and bus bridges that allow interconnecting bus masters with bus slaves (see *Figure 3*).

3.29.2 Advanced-control timers (TIM1, TIM8)

The advanced-control timers (TIM1, TIM8) can be seen as three-phase PWM generators multiplexed on 6 channels. They have complementary PWM outputs with programmable inserted dead times. They can also be considered as complete general-purpose timers. Their 4 independent channels can be used for:

- Input capture
- Output compare
- PWM generation (Edge- or Center-aligned modes)
- One-pulse mode output

If configured as standard 16-bit timers, they have the same features as the general-purpose TIMx timers. If configured as 16-bit PWM generators, they have full modulation capability (0-100%).

The advanced-control timer can work together with the TIMx timers via the Timer Link feature for synchronization or event chaining.

TIM1 and TIM8 support independent DMA request generation.

3.29.3 General-purpose timers (TIMx)

There are ten synchronizable general-purpose timers embedded in the STM32H750xB devices (see *Table 4* for differences).

- **TIM2, TIM3, TIM4, TIM5**

  The devices include 4 full-featured general-purpose timers: TIM2, TIM3, TIM4 and TIM5. TIM2 and TIM5 are based on a 32-bit auto-reload up/downcounter and a 16-bit prescaler while TIM3 and TIM4 are based on a 16-bit auto-reload up/downcounter and a 16-bit prescaler. All timers feature 4 independent channels for input capture/output compare, PWM or One-pulse mode output. This gives up to 16 input capture/output compare/PWMs on the largest packages.

  TIM2, TIM3, TIM4 and TIM5 general-purpose timers can work together, or with the other general-purpose timers and the advanced-control timers TIM1 and TIM8 via the Timer Link feature for synchronization or event chaining.

  Any of these general-purpose timers can be used to generate PWM outputs.

  TIM2, TIM3, TIM4, TIM5 all have independent DMA request generation. They are capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 4 hall-effect sensors.

- **TIM12, TIM13, TIM14, TIM15, TIM16, TIM17**

  These timers are based on a 16-bit auto-reload upcounter and a 16-bit prescaler. TIM13, TIM14, TIM16 and TIM17 feature one independent channel, whereas TIM12 and TIM15 have two independent channels for input capture/output compare, PWM or One-pulse mode output. They can be synchronized with the TIM2, TIM3, TIM4, TIM5 full-featured general-purpose timers or used as simple timebases.

3.36 SPDIFRX Receiver Interface (SPDIFRX)

The SPDIFRX peripheral is designed to receive an S/PDIF flow compliant with IEC-60958 and IEC-61937. These standards support simple stereo streams up to high sample rate, and compressed multi-channel surround sound, such as those defined by Dolby or DTS (up to 5.1).

The main SPDIFRX features are the following:

- Up to 4 inputs available
- Automatic symbol rate detection
- Maximum symbol rate: 12.288 MHz
- Stereo stream from 32 to 192 kHz supported
- Supports Audio IEC-60958 and IEC-61937, consumer applications
- Parity bit management
- Communication using DMA for audio samples
- Communication using DMA for control and user channel information
- Interrupt capabilities

The SPDIFRX receiver provides all the necessary features to detect the symbol rate, and decode the incoming data stream. The user can select the wanted SPDIF input, and when a valid signal will be available, the SPDIFRX will re-sample the incoming signal, decode the Manchester stream, recognize frames, sub-frames and blocks elements. It delivers to the CPU decoded data, and associated status flags.

The SPDIFRX also offers a signal named spdif_frame_sync, which toggles at the S/PDIF sub-frame rate that will be used to compute the exact sample rate for clock drift algorithms.

3.37 Single wire protocol master interface (SWPMI)

The Single wire protocol master interface (SWPMI) is the master interface corresponding to the Contactless Frontend (CLF) defined in the ETSI TS 102 613 technical specification. The main features are:

- Full-duplex communication mode
- automatic SWP bus state management (active, suspend, resume)
- configurable bitrate up to 2 Mbit/s
- automatic SOF, EOF and CRC handling

SWPMI can be served by the DMA controller.

Table 7. STM32H750xB pin/ball definition (continued)

Pin/ball name			Pin name (function after reset)	Pin type	I/O structure	Notes	Alternate functions	Additional functions
LQFP100	UFBGA176+25	TFBGA240 +25						
9	F1	C1	PC15-OSC32_OUT (OSC32_OUT)(1)	I/O	FT	-	EVENTOUT	OSC32_ OUT
-	D3	E2	PI9	I/O	FT_h	-	UART4_RX, FDCAN1_RX, FMC_D30, LCD_VSYNC, EVENTOUT	-
-	E3	F3	PI10	I/O	FT_h	-	FDCAN1_RXFD_MODE, ETH_MII_RX_ER, FMC_D31, LCD_HSYNC, EVENTOUT	
-	E4	F4	PI11	I/O	FT	-	LCD_G6, OTG_HS_ULPI_DIR, EVENTOUT	WKUP4
-	F2	A17	VSS	S	-	-	-	-
-	F3	E6	VDD	S	-	-	-	-
-	-	E1(2)	NC	-	-	-	-	-
-	-	F1(3)	NC	-	-	-	-	-
-	-	G2(4)	NC	-	-	-	-	-
-	E2	G4	PF0	I/O	FT_f	-	I2C2_SDA, FMC_A0, EVENTOUT	-
-	H3	G3	PF1	I/O	FT_f	-	I2C2_SCL, FMC_A1, EVENTOUT	-
-	H2	G1	PF2	I/O	FT	-	I2C2_SMBA, FMC_A2, EVENTOUT	-
-	-	H1	PI12	I/O	FT	-	ETH_TX_ER, LCD_HSYNC, EVENTOUT	-
-	-	H2	PI13	I/O	FT	-	LCD_VSYNC, EVENTOUT	-
-	-	H3	PI14	I/O	FT_h	-	LCD_CLK, EVENTOUT	-
-	J2	H4	PF3	I/O	FT_ha	-	FMC_A3, EVENTOUT	ADC3_INP5
-	J3	J5	PF4	I/O	FT_ha	-	FMC_A4, EVENTOUT	ADC3_INN5, ADC3_INP9
-	K3	J4	PF5	I/O	FT_ha	-	FMC_A5, EVENTOUT	ADC3_INP4
10	G2	C10	VSS	S	-	-	-	-
11	G3	E9	VDD	S	-	-	-	-
-	K2	K2	PF6	I/O	FT_ha	-	TIM16_CH1, SPI5_NSS, SAI1_SD_B, UART7_RX, SAI4_SD_B, QUADSPI_BK1_IO3, EVENTOUT	ADC3_INN4, ADC3_INP8
-	K1	K3	PF7	I/O	FT_ha	-	TIM17_CH1, SPI5_SCK, SAI1_MCLK_B, UART7_TX, SAI4_MCLK_B, QUADSPI_BK1_IO2, EVENTOUT	ADC3_INP3

Table 7. STM32H750xB pin/ball definition (continued)

Pin/ball name			Pin name (function after reset)	Pin type	I/O structure	Notes	Alternate functions	Additional functions
LQFP100	UFBGA176+25	TFBGA240 +25						
46	R12	P11	PB10	I/O	FT_f	-	TIM2_CH3, HRTIM_SCOUT, LPTIM2_IN1, I2C2_SCL, SPI2_SCK/I2S2_CK, DFSDM_DATIN7, USART3_TX, QUADSPI_BK1_NCS, OTG_HS_ULPI_D3, ETH_MII_RX_ER, LCD_G4, EVENTOUT	-
47	R13	P12	PB11	I/O	FT_f	-	TIM2_CH4, HRTIM_SCIN, LPTIM2_ETR, I2C2_SDA, DFSDM_CKIN7, USART3_RX, OTG_HS_ULPI_D4, ETH_MII_TX_EN/ETH_RMII_TX_EN, LCD_G5, EVENTOUT	-
48	M10	U11	VCAPVCAP	S	-	-	-	-
49	K7	L15	VSS	S	-	-	-	-
-	-	U12	VDDLDO	S	-	-	-	-
50	N10	L13	VDD	S	-	-	-	-
-	-	R12	PJ5	I/O	FT	-	LCD_R6, EVENTOUT	-
-	M11	T11	PH6	I/O	FT	-	TIM12_CH1, I2C2_SMBA, SPI5_SCK, ETH_MII_RXD2, FMC_SDNE1, DCMI_D8, EVENTOUT	-
-	N12	U13	PH7	I/O	FT_fa	-	I2C3_SCL, SPI5_MISO, ETH_MII_RXD3, FMC_SDCKE1, DCMI_D9, EVENTOUT	-
-	M12	T13	PH8	I/O	FT_fha	-	TIM5_ETR, I2C3_SDA, FMC_D16, DCMI_HSYNC, LCD_R2, EVENTOUT	-
-	F8	M15	VSS	S	-	-	-	-
-	-	M13	VDD	S	-	-	-	-
-	M13	R13	PH9	I/O	FT_h	-	TIM12_CH2, I2C3_SMBA, FMC_D17, DCMI_D0, LCD_R3, EVENTOUT	-
-	L13	P13	PH10	I/O	FT_h	-	TIM5_CH1, I2C4_SMBA, FMC_D18, DCMI_D1, LCD_R4, EVENTOUT	-
-	L12	P14	PH11	I/O	FT_fh	-	TIM5_CH2, I2C4_SCL, FMC_D19, DCMI_D2, LCD_R5, EVENTOUT	-
-	K12	R14	PH12	I/O	FT_fh	-	TIM5_CH3, I2C4_SDA, FMC_D20, DCMI_D3, LCD_R6, EVENTOUT	-

Table 7. STM32H750xB pin/ball definition (continued)

Pin/ball name			Pin name (function after reset)	Pin type	I/O structure	Notes	Alternate functions	Additional functions
LQFP100	UFBGA176+25	TFBGA240 +25						
-	E14	A16	PI0	I/O	FT_h	-	TIM5_CH4, SPI2_NSS/I2S2_WS, FDCAN1_RXFD_MODE, FMC_D24, DCMI_D13, LCD_G5, EVENTOUT	-
-	G9	-	VSS	S	-	-	-	-
-	D14	A15	PI1	I/O	FT_h	-	TIM8_BKIN2, SPI2_SCK/I2S2_CK, TIM8_BKIN2_COMP12, FMC_D25, DCMI_D8, LCD_G6, EVENTOUT	-
-	C14	B15	PI2	I/O	FT_h	-	TIM8_CH4, SPI2_MISO/I2S2_SDI, FMC_D26, DCMI_D9, LCD_G7, EVENTOUT	-
-	C13	C14	PI3	I/O	FT_h	-	TIM8_ETR, SPI2_MOSI/I2S2_SDO, FMC_D27, DCMI_D10, EVENTOUT	-
-	D9	-	VSS	S	-	-	-	-
-	C9	-	VDD	S	-	-	-	-
76	A14	B14	PA14 (JTCK/SWCLK)	I/O	FT	-	JTCK-SWCLK, EVENTOUT	-
77	A13	A14	PA15 (JTDI)	I/O	FT	-	JTDI, TIM2_CH1/TIM2_ETR, HRTIM_FLT1, HDMI_CEC, SPI1_NSS/I2S1_WS, SPI3_NSS/I2S3_WS, SPI6_NSS, UART4_RTS, UART7_TX, EVENTOUT	-
78	B14	A13	PC10	I/O	FT_ha	-	HRTIM_EEV1, DFSDM_CKIN5, SPI3_SCK/I2S3_CK, USART3_TX, UART4_TX, QUADSPI_BK1_IO1, SDMMC1_D2, DCMI_D8, LCD_R2, EVENTOUT	-
79	B13	B13	PC11	I/O	FT_h	-	HRTIM_FLT2, DFSDM_DATIN5, SPI3_MISO/I2S3_SDI, USART3_RX, UART4_RX, QUADSPI_BK2_NCS, SDMMC1_D3, DCMI_D4, EVENTOUT	-
80	A12	C12	PC12	I/O	FT_h	-	TRACED3, HRTIM_EEV2, SPI3_MOSI/I2S3_SDO, USART3_CK, UART5_TX, SDMMC1_CK, DCMI_D9, EVENTOUT	-

Table 13. Port F alternate functions

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
		SYS	TIM1/2/16/17/LPTIM1/HRTIM1	SAI1/TIM3/4/5/12/HRTIM1	LPUART/TIM8/LPTIM2/3/4/5/HRTIM1/DFSDM	I2C1/2/3/4/USART1/TIM15/LPTIM2/DFSDM/CEC	SPI1/2/3/4/5/6/CEC	SPI2/3/SAI1/3/I2C4/UART4/DFSDM	SPI2/3/6/USART1/2/3/6/UART7/SDMMC1	SPI6/SAI2/4/UART4/5/8/LPUART/SDMMC1/SPDIFRX	SAI4/FDCAN1/2/TIM13/14/QUADSPI/FMC/SDMMC2/LCD/SPDIFRX	SAI2/4/TIM8/QUADSPI/SDMMC2/OTG1_HS/OTG2_FS/LCD	I2C4/UART7/SWPMI1/TIM1/8/DFSDM/SDMMC2/MDIOS/ETH	TIM1/8/FMC/SDMMC1/MDIOS/OTG1_FS/LCD	TIM1/DCMI/LCD/COMP	UART5/LCD	SYS
Port F	PF0	-	-	-	-	I2C2_SDA	-	-	-	-	-	-	-	FMC_A0	-	-	EVENT-OUT
	PF1	-	-	-	-	I2C2_SCL	-	-	-	-	-	-	-	FMC_A1	-	-	EVENT-OUT
	PF2	-	-	-	-	I2C2_SMBA	-	-	-	-	-	-	-	FMC_A2	-	-	EVENT-OUT
	PF3	-	-	-	-	-	-	-	-	-	-	-	-	FMC_A3	-	-	EVENT-OUT
	PF4	-	-	-	-	-	-	-	-	-	-	-	-	FMC_A4	-	-	EVENT-OUT
	PF5	-	-	-	-	-	-	-	-	-	-	-	-	FMC_A5	-	-	EVENT-OUT
	PF6	-	TIM16_CH1	-	-	-	SPI5_NSS	SAI1_SD_B	UART7_RX	SAI4_SD_B	QUADSPI_BK1_IO3	-	-	-	-	-	EVENT-OUT
	PF7	-	TIM17_CH1	-	-	-	SPI5_SCK	SAI1_MCLK_B	UART7_TX	SAI4_MCLK_B	QUADSPI_BK1_IO2	-	-	-	-	-	EVENT-OUT
	PF8	-	TIM16_CH1N	-	-	-	SPI5_MISO	SAI1_SCK_B	UART7_RTS	SAI4_SCK_B	TIM13_CH1	QUADSPI_BK1_IO0	-	-	-	-	EVENT-OUT
	PF9	-	TIM17_CH1N	-	-	-	SPI5_MOSI	SAI1_FS_B	UART7_CTS	SAI4_FS_B	TIM14_CH1	QUADSPI_BK1_IO1	-	-	-	-	EVENT-OUT
	PF10	-	TIM16_BKIN	SAI1_D3	-	-	-	-	-	-	QUADSPI_CLK	SAI4_D3	-	-	DCMI_D11	LCD_DE	EVENT-OUT
	PF11	-	-	-	-	-	SPI5_MOSI	-	-	-	-	SAI2_SD_B	-	FMC_SDNRAS	DCMI_D12	-	EVENT-OUT
	PF12	-	-	-	-	-	-	-	-	-	-	-	-	FMC_A6	-	-	EVENT-OUT
	PF13	-	-	-	DFSDM_DATIN6	I2C4_SMBA	-	-	-	-	-	-	-	FMC_A7	-	-	EVENT-OUT
	PF14	-	-	-	DFSDM_CKIN6	I2C4_SCL	-	-	-	-	-	-	-	FMC_A8	-	-	EVENT-OUT
	PF15	-	-	-	-	I2C4_SDA	-	-	-	-	-	-	-	FMC_A9	-	-	EVENT-OUT

Table 18. Port K alternate functions

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
		SYS	TIM1/2/16/17/LPTIM1/ HRTIM1	SAI1/TIM3/4/5/12/ HRTIM1	LPUART/ TIM8/ LPTIM2/3/4/5/HRTIM1/ DFSDM	I2C1/2/3/4/ USART1/ TIM15/ LPTIM2/ DFSDM/CEC	SPI1/2/3/4/5/6/CEC	SPI2/3/SAI1/3/I2C4/ UART4/ DFSDM	SPI2/3/6/ USART1/2/3/6/UART7/ SDMMC1	SPI6/SAI2/4/UART4/5/8/LPUART/ SDMMC1/ SPDIFRX	SAI4/ FDCAN1/2/ TIM13/14/ QUADSPI/ FMC/ SDMMC2/ LCD/ SPDIFRX	SAI2/4/ TIM8/ QUADSPI/ SDMMC2/ OTG1_HS/ OTG2_FS/ LCD	I2C4/ UART7/ SWPMI1/ TIM1/8/ DFSDM/ SDMMC2/ MDIOS/ ETH	TIM1/8/FMC/SDMMC1/ MDIOS/ OTG1_FS/ LCD	TIM1/DCMI/LCD/ COMP	UART5/ LCD	SYS
Port K	PK0	-	TIM1_CH1N	-	TIM8_CH3	-	SPI5_SCK	-	-	-	-	-	-	-	-	LCD_G5	EVENT-OUT
	PK1	-	TIM1_CH1	-	TIM8_ CH3N	-	SPI5_NSS	-	-	-	-	-	-	-	-	LCD_G6	EVENT-OUT
	PK2	-	TIM1_BKIN	-	TIM8_BKIN	-	-	-	-	-	-	TIM8_BKIN_COMP12	TIM1_BKIN_COMP12	-	-	LCD_G7	EVENT-OUT
	PK3	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_B4	EVENT-OUT
	PK4	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_B5	EVENT-OUT
	PK5	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_B6	EVENT-OUT
	PK6	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_B7	EVENT-OUT
	PK7	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_DE	EVENT-OUT

Table 37. Peripheral current consumption in Run mode

Peripheral		I_{DD}(Typ)			Unit
		VOS1	VOS2	VOS3	
AHB3	MDMA	8.3	7.6	7	µA/MHz
	DMA2D	21	20	18	
	JPEG	24	23	21	
	FLASH	9.9	9	8.3	
	FMC registers	0.9	0.9	0.8	
	FMC kernel	6.1	5.5	5.3	
	QUADSPI registers	1.5	1.4	1.3	
	QUADSPI kernel	0.9	0.8	0.7	
	SDMMC1 registers	8	7.2	6.8	
	SDMMC1 kernel	2.4	2	1.8	
	DTCM1	5.7	5	4.5	
	DTCM2	5.5	4.8	4.3	
	ITCM	3.2	2.9	2.6	
	D1SRAM1	7.6	6.8	6.1	
	Bridge AHB3	7.5	6.8	6.3	
AHB1	DMA1	1.1	1	1	
	DMA2	1.7	1.4	1.1	
	ADC1/2 registers	3.9	3.2	3.1	
	ADC1/2 kernel	0.9	0.8	0.7	
	ART	5.5	4.5	4.2	
	ETH1MAC	16	14	13	
	ETH1TX				
	ETH1RX				
	USB1OTG registers	15	14	13	
	USB1OTG kernel	-	8.5	8.5	
	USB1ULPI	0.3	0.3	0.1	
	USB2OTG registers	15	13	12	
	USB2OTG kernel	-	8.6	8.6	
	USB2ULPI	16	16	16	
	Bridge AHB1	10	9.6	8.6	

Table 37. Peripheral current consumption in Run mode (continued)

Peripheral		I_{DD}(Typ)			Unit
		VOS1	VOS2	VOS3	
APB2	TIM1	5.1	4.8	4.3	µA/MHz
	TIM8	5.4	4.9	4.6	
	USART1 registers	2.7	2.6	2.5	
	USART1 kernel	0.1	0.1	0.1	
	USART6 registers	2.6	2.5	2.5	
	USART6 kernel	0.1	0.1	0.1	
	SPI1 registers	1.8	1.6	1.6	
	SPI1 kernel	1	0.8	0.6	
	SPI4 registers	1.6	1.5	1.5	
	SPI4 kernel	0.5	0.4	0.4	
	TIM15	3.1	2.8	2.7	
	TIM16	2.4	2.1	2.1	
	TIM17	2.2	2	1.9	
	SPI5 registers	1.8	1.7	1.7	
	SPI5 kernel	0.6	0.5	0.3	
	SAI1 registers	1.5	1.4	1.4	
	SAI1 kernel	2	1.7	1.5	
	SAI2 registers	1.5	1.5	1.3	
	SAI2 kernel	2.2	1.9	1.8	
	SAI3 registers	1.8	1.6	1.6	
	SAI3 kernel	2.5	2.3	2.1	
	DFSDM1 registers	6	5.4	5.2	
	DFSDM1 kernel	0.9	0.8	0.7	
	HRTIM	40	37	35	
	Bridge APB2	0.1	0.1	0.1	

Table 46. CSI oscillator characteristics(1) (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{stab(CSI)}$	CSI oscillator stabilization time (to reach ±3% of f_{CSI})	-	-	-	4	cycle
$I_{DD(CSI)}$	CSI oscillator power consumption	-	-	23	30	µA

1. Guaranteed by design.
2. Guaranteed by test in production.
3. Guaranteed by characterization.

Low-speed internal (LSI) RC oscillator

Table 47. LSI oscillator characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{LSI}(1)	LSI frequency	V_{DD} = 3.3 V, T_J = 25 °C (after calibration)	31.4	32	32.6	kHz
		T_J = –40 to 105 °C, V_{DD} = 1.62 to 3.6 V	29.76	-	33.60	
$t_{su(LSI)}$(2)	LSI oscillator startup time	-	-	80	130	µs
$t_{stab(LSI)}$(2)	LSI oscillator stabilization time (5% of final value)	-	-	120	170	
$I_{DD(LSI)}$(2)	LSI oscillator power consumption	-	-	130	280	nA

1. Guaranteed by characterization results.
2. Guaranteed by design.

6.3.10 PLL characteristics

The parameters given in *Table 48* are derived from tests performed under temperature and V_{DD} supply voltage conditions summarized in *Table 22: General operating conditions*.

Table 48. PLL characteristics (wide VCO frequency range)(1)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{PLL_IN}	PLL input clock	-	2	-	16	MHz
	PLL input clock duty cycle	-	10	-	90	%
$f_{PLL\_P\_OUT}$	PLL multiplier output clock P	Voltage scaling range 1	1.5	-	400(2)	MHz
		Voltage scaling range 2	1.5	-	300	
		Voltage scaling range 3	1.5	-	200	
$f_{PLL\_Q\_OUT}$	PLL multiplier output clock Q/R	Voltage scaling range 1	1.5	-	400(2)	
		Voltage scaling range 2	1.5	-	300	
		Voltage scaling range 3	1.5	-	200	
f_{VCO_OUT}	PLL VCO output	-	192	-	836	

Static latchup

Two complementary static tests are required on six parts to assess the latchup performance:

- A supply overvoltage is applied to each power supply pin
- A current injection is applied to each input, output and configurable I/O pin

These tests are compliant with JESD78 IC latchup standard.

Table 56. Electrical sensitivities

Symbol	Parameter	Conditions	Class
LU	Static latchup class	T_A = +25 °C conforming to JESD78	II level A

6.3.14 I/O current injection characteristics

As a general rule, a current injection to the I/O pins, due to external voltage below V_{SS} or above V_{DD} (for standard, 3.3 V-capable I/O pins) should be avoided during the normal product operation. However, in order to give an indication of the robustness of the microcontroller in cases when an abnormal injection accidentally happens, susceptibility tests are performed on a sample basis during the device characterization.

Functional susceptibilty to I/O current injection

While a simple application is executed on the device, the device is stressed by injecting current into the I/O pins programmed in floating input mode. While current is injected into the I/O pin, one at a time, the device is checked for functional failures.

The failure is indicated by an out of range parameter: ADC error above a certain limit (higher than 5 LSB TUE), out of conventional limits of induced leakage current on adjacent pins (out of –5 µA/+0 µA range), or other functional failure (for example reset, oscillator frequency deviation).

The following tables are the compilation of the SIC1/SIC2 and functional ESD results.

Negative induced A negative induced leakage current is caused by negative injection and positive induced leakage current by positive injection.

Table 57. I/O current injection susceptibility(1)

Symbol	Description	Functional susceptibility		Unit
		Negative injection	Positive injection	
I_{INJ}	PA7, PC5, PG1, PB14, PJ7, PA11, PA12, PA13, PA14, PA15, PJ12, PB4	5	0	mA
	PA2, PH2, PH3, PE8, PA6, PA7, PC4, PE7, PE10, PE11	0	NA	
	PA0, PA_C, PA1, PA1_C, PC2, PC2_C, PC3, PC3_C, PA4, PA5, PH4, PH5, BOOT0	0	0	
	All other I/Os	5	NA	

1. Guaranteed by characterization.

Output buffer timing characteristics (HSLV option disabled)

The HSLV bit of SYSCFG_CCCSR register can be used to optimize the I/O speed when the product voltage is below 2.5 V.

Table 60. Output timing characteristics (HSLV OFF)(1)

Speed	Symbol	Parameter	conditions	Min	Max	Unit
00	F_{max}(2)	Maximum frequency	C=50 pF, 2.7 V≤ V_{DD}≤3.6 V	-	12	MHz
			C=50 pF, 1.62 V≤V_{DD}≤2.7 V	-	3	
			C=30 pF, 2.7 V≤V_{DD}≤3.6 V	-	12	
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V	-	3	
			C=10 pF, 2.7 V≤V_{DD}≤3.6 V	-	16	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V	-	4	
	t_r/t_f(3)	Output high to low level fall time and output low to high level rise time	C=50 pF, 2.7 V≤ V_{DD}≤3.6 V	-	16.6	ns
			C=50 pF, 1.62 V≤V_{DD}≤2.7 V	-	33.3	
			C=30 pF, 2.7 V≤V_{DD}≤3.6 V	-	13.3	
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V	-	25	
			C=10 pF, 2.7 V≤V_{DD}≤3.6 V	-	10	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V	-	20	
01	F_{max}(2)	Maximum frequency	C=50 pF, 2.7 V≤ V_{DD}≤3.6 V	-	60	MHz
			C=50 pF, 1.62 V≤V_{DD}≤2.7 V	-	15	
			C=30 pF, 2.7 V≤V_{DD}≤3.6 V	-	80	
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V	-	15	
			C=10 pF, 2.7 V≤V_{DD}≤3.6 V	-	110	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V	-	20	
	t_r/t_f(3)	Output high to low level fall time and output low to high level rise time	C=50 pF, 2.7 V≤ V_{DD}≤3.6 V	-	5.2	ns
			C=50 pF, 1.62 V≤V_{DD}≤2.7 V	-	10	
			C=30 pF, 2.7 V≤V_{DD}≤3.6 V	-	4.2	
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V	-	7.5	
			C=10 pF, 2.7 V≤V_{DD}≤3.6 V	-	2.8	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V	-	5.2	

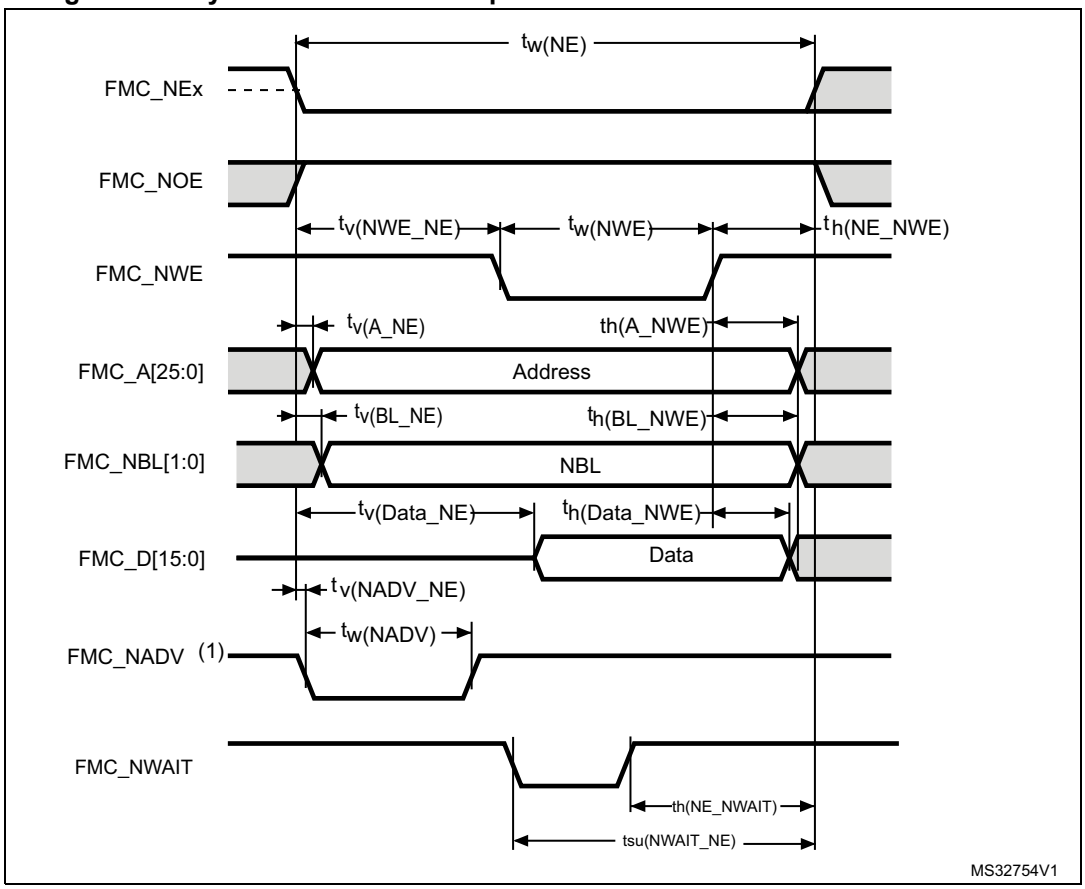
Output buffer timing characteristics (HSLV option enabled)

Table 61. Output timing characteristics (HSLV ON)(1)

Speed	Symbol	Parameter	conditions	Min	Max	Unit
00	F_{max}(2)	Maximum frequency	C=50 pF, 1.62 V≤V_{DD}≤2.7 V	-	10	MHz
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V	-	10	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V	-	10	
	t_r/t_f(3)	Output high to low level fall time and output low to high level rise time	C=50 pF, 1.62 V≤V_{DD}≤2.7 V	-	11	ns
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V	-	9	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V	-	6.6	
01	F_{max}(2)	Maximum frequency	C=50 pF, 1.62 V≤V_{DD}≤2.7 V	-	50	MHz
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V	-	58	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V	-	66	
	t_r/t_f(3)	Output high to low level fall time and output low to high level rise time	C=50 pF, 1.62 V≤V_{DD}≤2.7 V	-	6.6	ns
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V	-	4.8	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V	-	3	
10	F_{max}(2)	Maximum frequency	C=50 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	55	MHz
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	80	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	133	
	t_r/t_f(3)	Output high to low level fall time and output low to high level rise time	C=50 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	5.8	ns
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	4	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	2.4	
11	F_{max}(2)	Maximum frequency	C=50 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	60	MHz
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	90	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	175	
	t_r/t_f(3)	Output high to low level fall time and output low to high level rise time	C=50 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	5.3	ns
			C=30 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	3.6	
			C=10 pF, 1.62 V≤V_{DD}≤2.7 V(4)	-	1.9	

1. Guaranteed by design.
2. The maximum frequency is defined with the following conditions:
   (t_r+t_f) ≤ 2/3 T
   Skew ≤ 1/20 T
   45%<Duty cycle<55%
3. The fall and rise times are defined between 90% and 10% and between 10% and 90% of the output waveform, respectively.
4. Compensation system enabled.

Figure 19. Asynchronous non-multiplexed SRAM/PSRAM/NOR write waveforms



1. Mode 2/B, C and D only. In Mode 1, FMC_NADV is not used.

Table 65. Asynchronous non-multiplexed SRAM/PSRAM/NOR write timings(1)

Symbol	Parameter	Min	Max	Unit
$t_{w(NE)}$	FMC_NE low time	$3T_{fmc\_ker\_ck} - 1$	$3T_{fmc\_ker\_ck}$	ns
$t_{v(NWE\_NE)}$	FMC_NEx low to FMC_NWE low	$T_{fmc\_ker\_ck}$	$T_{fmc\_ker\_ck} + 1$	
$t_{w(NWE)}$	FMC_NWE low time	$T_{fmc\_ker\_ck} - 0.5$	$T_{fmc\_ker\_ck} + 0.5$	
$t_{h(NE\_NWE)}$	FMC_NWE high to FMC_NE high hold time	$T_{fmc\_ker\_ck}$	-	
$t_{v(A\_NE)}$	FMC_NEx low to FMC_A valid	-	2	
$t_{h(A\_NWE)}$	Address hold time after FMC_NWE high	$T_{fmc\_ker\_ck} - 0.5$	-	
$t_{v(BL\_NE)}$	FMC_NEx low to FMC_BL valid	-	0.5	
$t_{h(BL\_NWE)}$	FMC_BL hold time after FMC_NWE high	$T_{fmc\_ker\_ck} - 0.5$	-	
$t_{v(Data\_NE)}$	Data to FMC_NEx low to Data valid	-	$T_{fmc\_ker\_ck} + 2.5$	
$t_{h(Data\_NWE)}$	Data hold time after FMC_NWE high	$T_{fmc\_ker\_ck}+0.5$	-	
$t_{v(NADV\_NE)}$	FMC_NEx low to FMC_NADV low	-	0	
$t_{w(NADV)}$	FMC_NADV low time	-	$T_{fmc\_ker\_ck} + 1$	

1. Guaranteed by characterization results.

Figure 22. Synchronous multiplexed NOR/PSRAM read timings

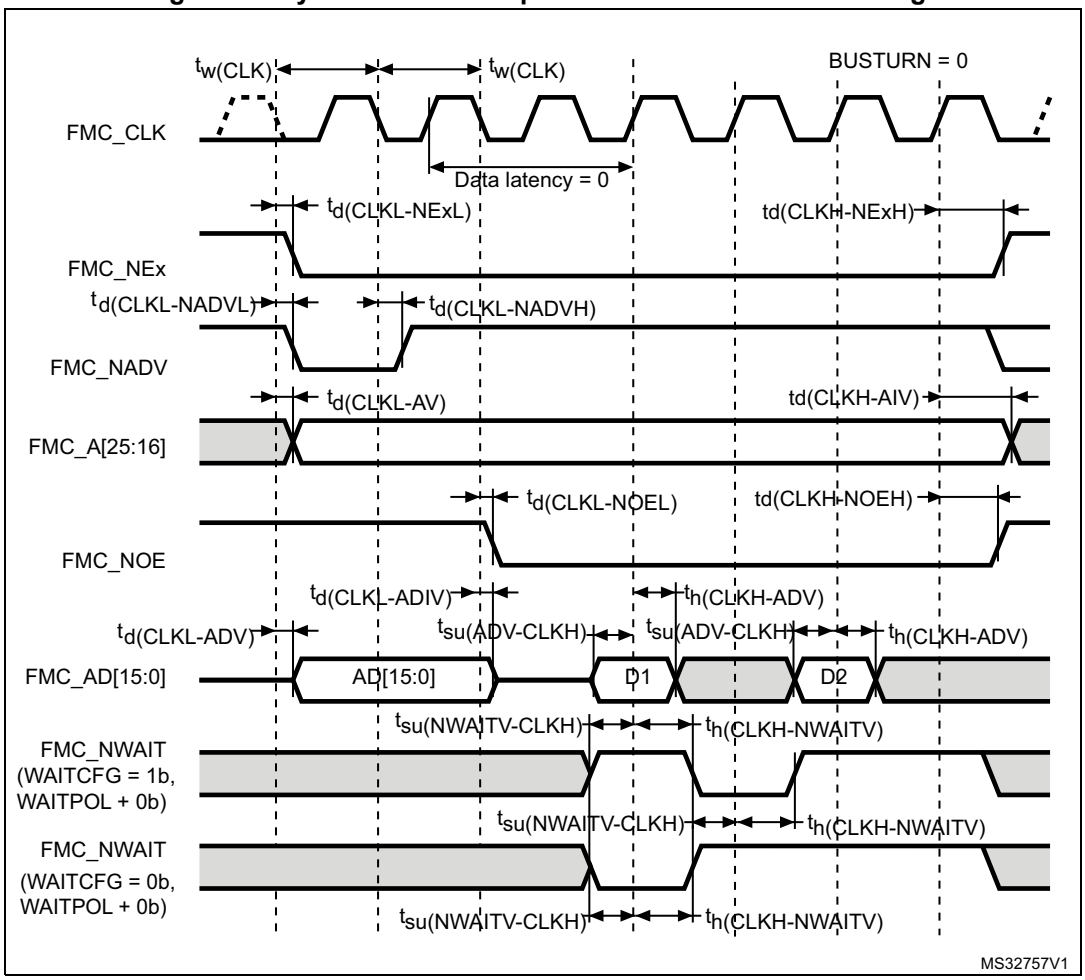


Figure 25. Synchronous non-multiplexed PSRAM write timings

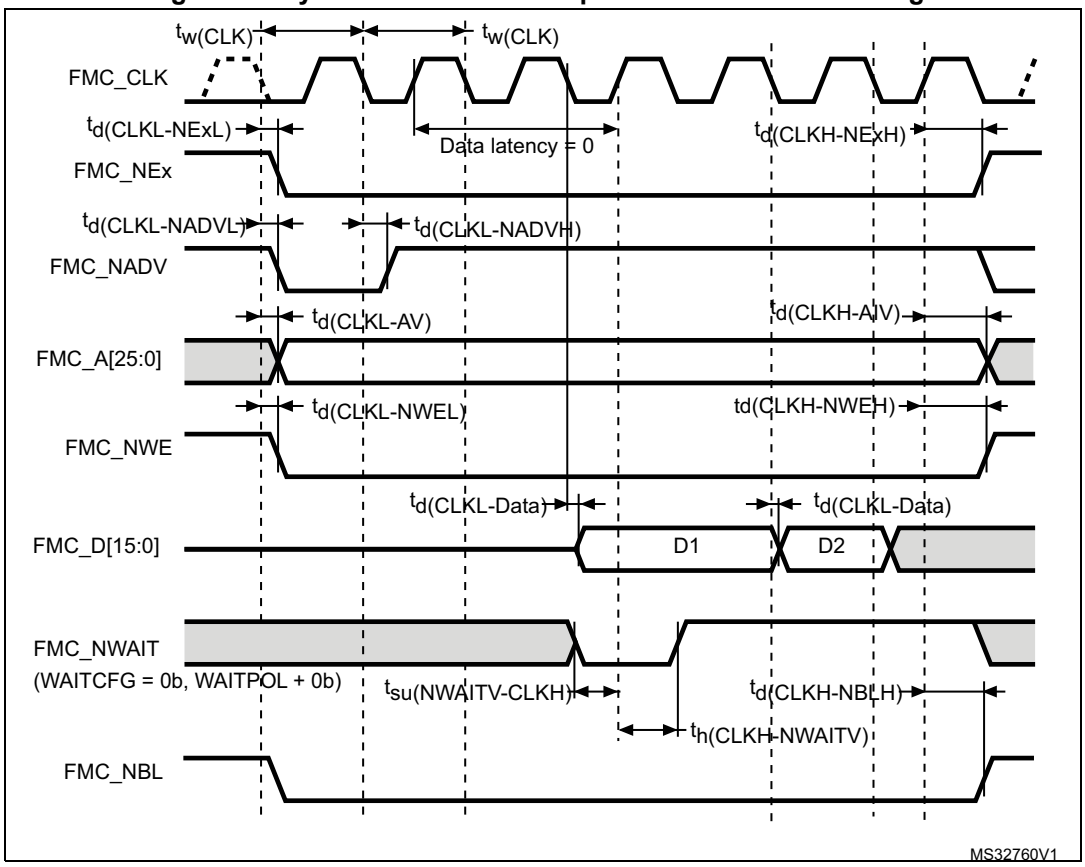


Table 74. Synchronous non-multiplexed PSRAM write timings(1)

Symbol	Parameter	Min	Max	Unit
$t_{(CLK)}$	FMC_CLK period	$2T_{fmc\_ker\_ck} - 1$	-	ns
$t_{d(CLKL-NExL)}$	FMC_CLK low to FMC_NEx low (x=0..2)	-	2	
$t_{(CLKH-NExH)}$	FMC_CLK high to FMC_NEx high (x= 0…2)	$T_{fmc\_ker\_ck} + 0.5$	-	
$t_{d(CLKL-NADVL)}$	FMC_CLK low to FMC_NADV low	-	0.5	
$t_{d(CLKL-NADVH)}$	FMC_CLK low to FMC_NADV high	0	-	
$t_{d(CLKL-AV)}$	FMC_CLK low to FMC_Ax valid (x=16…25)	-	2	
$t_{d(CLKH-AIV)}$	FMC_CLK high to FMC_Ax invalid (x=16…25)	$T_{fmc\_ker\_ck}$	-	
$t_{d(CLKL-NWEL)}$	FMC_CLK low to FMC_NWE low	-	1.5	
$t_{d(CLKH-NWEH)}$	FMC_CLK high to FMC_NWE high	$T_{fmc\_ker\_ck} + 1$	-	
$t_{d(CLKL-Data)}$	FMC_D[15:0] valid data after FMC_CLK low	-	3.5	
$t_{d(CLKL-NBLL)}$	FMC_CLK low to FMC_NBL low	-	2	
$t_{d(CLKH-NBLH)}$	FMC_CLK high to FMC_NBL high	$T_{fmc\_ker\_ck} + 1$	-	
$t_{su(NWAIT-CLKH)}$	FMC_NWAIT valid before FMC_CLK high	2	-	
$t_{h(CLKH-NWAIT)}$	FMC_NWAIT valid after FMC_CLK high	2	-	

1. Guaranteed by characterization results.

6.3.29 Camera interface (DCMI) timing specifications

Unless otherwise specified, the parameters given in *Table 97* for DCMI are derived from tests performed under the ambient temperature, $f_{rcc\_c\_ck}$ frequency and V_{DD} supply voltage summarized in *Table 22: General operating conditions*, with the following configuration:

- DCMI_PIXCLK polarity: falling
- DCMI_VSYNC and DCMI_HSYNC polarity: high
- Data formats: 14 bits
- Capacitive load C=30 pF
- Measurement points are done at CMOS levels: $0.5V_{DD}$

Table 97. DCMI characteristics(1)

Symbol	Parameter	Min	Max	Unit
-	Frequency ratio DCMI_PIXCLK/$f_{rcc\_c\_ck}$	-	0.4	-
DCMI_PIXCLK	Pixel clock input	-	80	MHz
D_{Pixel}	Pixel clock input duty cycle	30	70	%
$t_{su(DATA)}$	Data input setup time	1	-	ns
$t_{h(DATA)}$	Data input hold time	1	-	
$t_{su(HSYNC)}$ $t_{su(VSYNC)}$	DCMI_HSYNC/DCMI_VSYNC input setup time	1.5	-	
$t_{h(HSYNC)}$ $t_{h(VSYNC)}$	DCMI_HSYNC/DCMI_VSYNC input hold time	1	-	

1. Guaranteed by characterization results.

Figure 40. DCMI timing diagram

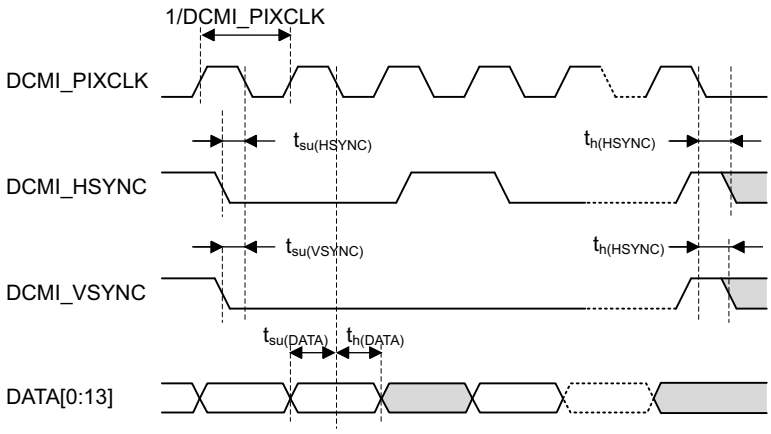


Figure 48. SAI master timing waveforms

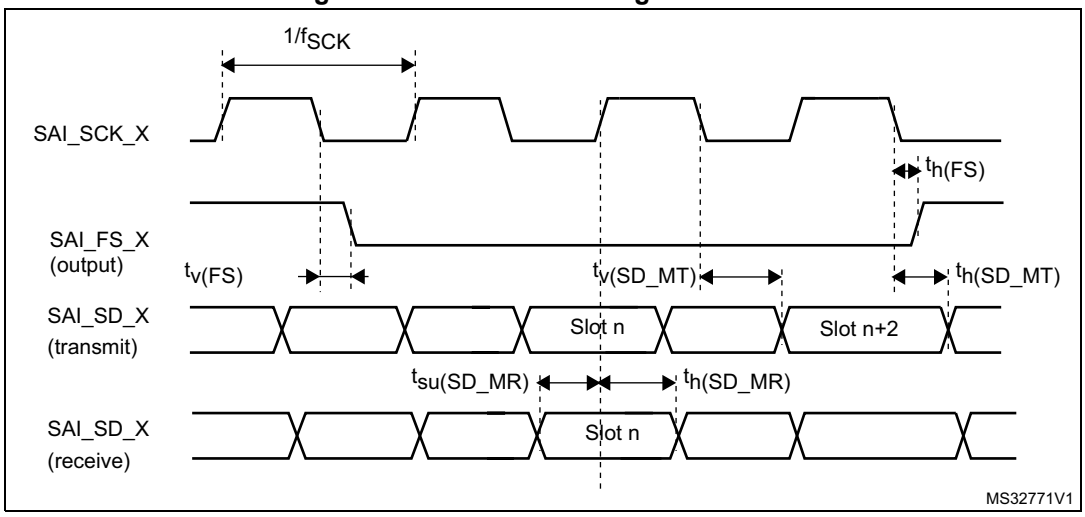
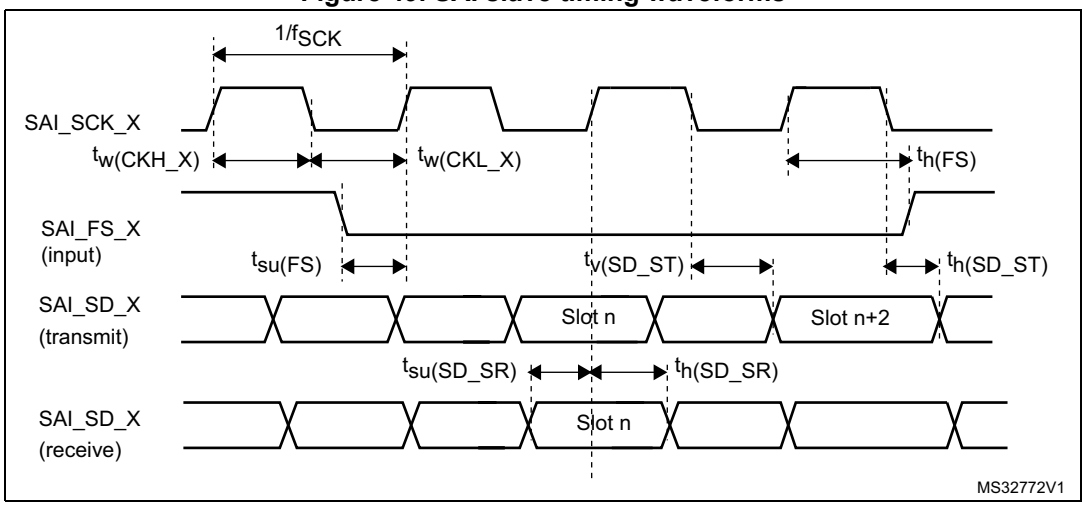


Figure 49. SAI slave timing waveforms



MDIO characteristics

Table 105. MDIO Slave timing parameters

Symbol	Parameter	Min	Typ	Max	Unit
F_{sDC}	Management data clock	-	-	40	MHz
$t_{d(MDIO)}$	Management data input/output **output valid time**	7	8	20	ns
$t_{su(MDIO)}$	Management data input/output **setup time**	4	-	-	
$t_{h(MDIO)}$	Management data input/output **hold time**	1	-	-	

The MDIO controller is mapped on APB2 domain. The frequency of the APB bus should at least 1.5 times the MDC frequency: $F_{PCLK2} \geq 1.5 * F_{MDC}$.